

# LP3990 150mA Linear Voltage Regulator for Digital Applications

### **General Description**

The LP3990 regulator is designed to meet the requirements of portable, battery-powered systems providing an accurate output voltage, low noise, and low quiescent current. The LP3990 will provide a 0.8V output from the low input voltage of 2V at up to 150mA load current. When switched into shutdown mode via a logic signal at the enable pin, the power consumption is reduced to virtually zero.

The LP3990 is designed to be stable with space saving ceramic capacitors as small as  $1.0\mu$ F.

Performance is specified for a -40°C to 125°C junction temperature range.

For output voltages other than 0.8V, 1.2, 1.35V, 1.5V, 1.8V, 2.5V, 2.8V, or 3.3V please contact your local NSC sales office.

### Features

- 1% Voltage Accuracy at Room Temperature
- Stable with Ceramic Capacitor
- Logic Controlled Enable
- No Noise Bypass Capacitor Required
- Thermal-Overload and Short-Circuit Protection

## Key Specifications

Input Voltage Range	2.0 to 6.0V
<ul> <li>Output Voltage Range</li> </ul>	0.8 to 3.3V
<ul> <li>Output Current</li> </ul>	150mA
<ul> <li>Output Stable - Capacitors</li> </ul>	1.0uF
<ul> <li>Virtually Zero I<sub>Q</sub> (Disabled)</li> </ul>	<10nA
<ul> <li>Very Low I<sub>Q</sub> (Enabled)</li> </ul>	43uA
Low Output Noise	150uV <sub>RMS</sub>
■ PSRR	55dB at 1kHz
<ul> <li>Fast Start Up</li> </ul>	105us

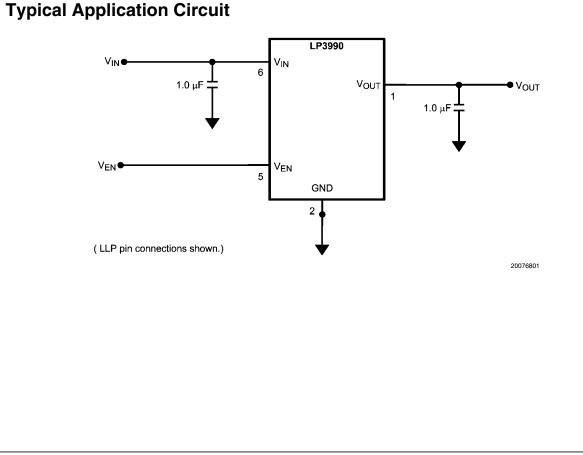
### Package

All available in Lead Free option. 4 Pin micro SMD 1 mm x 1.3 mm 6 pin LLP (SOT23 footprint) SOT23 - 5

For other package options contact your NSC sales office.

### **Applications**

- Cellular Handsets
- Hand-Held Information Appliances



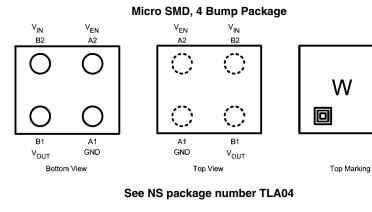
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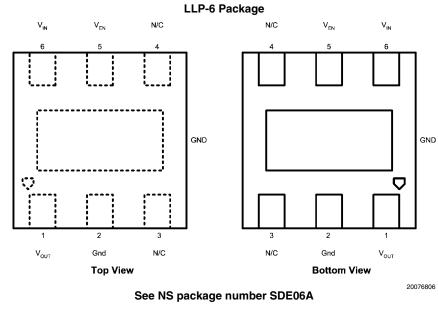
## **Pin Descriptions**

LP3990

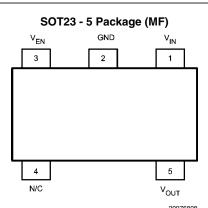
	Packages						
	Pin No		Symbol	Name and Function			
LLP	micro SMD	SOT23-5					
5	A2	3	V <sub>EN</sub>	Enable Input; Enables the Regulator when $\geq 0.95V$ .			
				Disables the Regulator when $\leq 0.4$ V.			
				Enable Input has $1M\Omega$ pulldown resistor to GND.			
2	A1	2	GND	Common Ground. Connect to Pad.			
1	B1	5	V <sub>OUT</sub>	Voltage output. A 1.0µF Low ESR Capacitor should be connected to this Pin. Connect this output to the load circuit.			
6	B2	1	V <sub>IN</sub>	Voltage Supply Input. A 1.0µF capacitor should be connected at this input.			
3		4	N/C	No Connection. Do not connect to any other pin.			
4			N/C	No Connection. Do not connect to any other pin.			
Pad			GND	Common Ground. Connect to Pin 2.			

### **Connection Diagrams**





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See NS package number MF05A

LP3990

## **Ordering Information**

### For micro SMD Package

Output Voltage (V)	Grade	LP3990 Supplied as 250 Units, Tape and Reel	LP3990 Supplied as 3000 Units, Tape and Reel	Package Marking
0.8	STD	LP3990TL-0.8	LP3990TLX-0.8	
1.2	STD	LP3990TL-1.2	LP3990TLX-1.2	
1.35	STD	LP3990TL-1.35	LP3990TLX-1.35	
1.5	STD	LP3990TL-1.5	LP3990TLX-1.5	
1.8	STD	LP3990TL-1.8	LP3990TLX-1.8	
2.5	STD	LP3990TL-2.5	LP3990TLX-2.5	
2.8	STD	LP3990TL-2.8	LP3990TLX-2.8	

#### For LLP-6 Package

Output Voltage (V)	Grade	LP3990 Supplied as 1000 Units, Tape and Reel	LP3990 Supplied as 3000 Units, Tape and Reel	Package Marking
0.8	STD	LP3990SD-0.8	LP3990SDX-0.8	L085B
1.2	STD	LP3990SD-1.2	LP3990SDX-1.2	L086B
1.35	STD	LP3990SD-1.35	LP3990SDX-1.35	L150B
1.5	STD	LP3990SD-1.5	LP3990SDX-1.5	L087B
1.8	STD	LP3990SD-1.8	LP3990SDX-1.8	L088B
2.5	STD	LP3990SD-2.5	LP3990SDX-2.5	L090B
2.8	STD	LP3990SD-2.8	LP3990SDX-2.8	L091B

#### For SOT23 - 5 Package

Output Voltage (V)	Grade	LP3990 Supplied as 1000 Units, Tape and Reel	LP3990 Supplied as 3000 Units, Tape and Reel	Package Marking
1.2	STD	LP3990MF-1.2	LP3990MFX-1.2	SCDB
1.5	STD	LP3990MF-1.5	LP3990MFX-1.5	SCEB
1.8	STD	LP3990MF-1.8	LP3990MFX-1.8	SCFB
2.5	STD	LP3990MF-2.5	LP3990MFX-2.5	SCJB
2.8	STD	LP3990MF-2.8	LP3990MFX-2.8	SCKB
3.3	STD	LP3990MF-3.3	LP3990MFX-3.3	SCLB

### **Absolute Maximum Ratings**

(Notes 1, 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Input Voltage	-0.3 to 6.5V
Output Voltage	-0.3 to (V <sub>IN</sub> + 0.3V) with
	6.5V (max)
Enable Input Voltage	-0.3 to (V <sub>IN</sub> + 0.3V) with
	6.5V (max)
Junction Temperature	150°C
Lead/Pad Temp. (Note 3)	
LLP/SOT23	235°C
micro SMD	260°C
Storage Temperature	-65 to 150°C
Continuous Power Dissipation	
Internally Limited(Note 4)	
ESD (Note 5)	

Human Body Model Machine Model

### 2KV 200V

LP3990

### Operating Ratings (Note 1)

Input Voltage	2V to 6V
Enable Input Voltage	0 to $(V_{IN} + 0.3V)$ with
	6.0V (max)
Junction Temperature	-40°C to 125°C
Ambient Temperature T <sub>A</sub> Range (Note 6)	-40°C to 85°C
(10010-0)	
Thermal Properties (	Note 1)

Junction To Ambient Thermal Resistance(Note 8)  $\theta_{JA}$ (LLP-6)  $\theta_{JA}$ (microSMD)  $\theta_{JA}$ SOT23-5

88°C/W 220°C/W 220°C/W

### **Electrical Characteristics**

Unless otherwise noted,  $V_{EN}$  =950mV,  $V_{IN}$  =  $V_{OUT}$  + 1.0V, or 2.0V, whichever is higher.  $C_{IN}$  = 1  $\mu$ F,  $I_{OUT}$  = 1 mA,  $C_{OUT}$  =0.47  $\mu$ F.

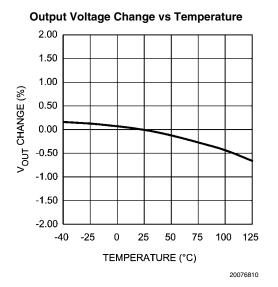
Typical values and limits appearing in normal type apply for  $T_J = 27^{\circ}$ C. Limits appearing in **boldface** type apply over the full junction temperature range for operation, -40 to +125^{\circ}C. (Note 13)

Symbol	Devemeter	Parameter     Conditions       put Voltage     (Note 14)		Tum	Limit		Units
Symbol	Parameter			Тур	Min	Max	Units
V <sub>IN</sub>	Input Voltage				2	6	V
ΔV <sub>OUT</sub>	Output Voltage Tolerance	I <sub>LOAD</sub> = 1 mA	Micro SMD		-1	+1	-
			LLP		-1.5	+1.5	
			SOT-23		-1.5	+1.5	%
		Over full line and	Micro SMD		-2.5	+2.5	/0
		load regulation.	LLP		-3	+3	
			SOT-23		-4	+4	
	Line Regulation Error	$V_{IN} = (V_{OUT(NOM)})$	+ 1.0V) to 6.0V,	0.02	-0.1	0.1	%/V
	Load Regulation Error	I <sub>OUT</sub> = 1mA to 150mA	V <sub>OUT</sub> = 0.8 to 1.95V MicroSMD	0.002	-0.005	0.005	
			V <sub>OUT</sub> = 0.8 to 1.95V LLP, SOT-23	0.003	-0.008	0.008	1
			V <sub>OUT</sub> = 2.0 to 3.3V MicroSMD	0.0005	-0.002	0.002	%/mA
			V <sub>OUT</sub> = 2.0 to 3.3V LLP, SOT-23	0.002	-0.005	0.005	
/ <sub>DO</sub>	Dropout Voltage	I <sub>OUT</sub> = 150mA (Notes 7, 10)		120		200	mV
LOAD	Load Current	(Notes 9, 10)			0		μA
Q	Quiescent Current	V <sub>EN</sub> = 950mV, I <sub>O</sub>	<sub>UT</sub> = 0mA	43		80	
		V <sub>EN</sub> = 950mV, I <sub>O</sub>	<sub>UT</sub> = 150mA	65		120	μΑ
		$V_{EN} = 0.4V$				0.2	-
sc	Short Circuit Current Limit	(Note 11)		550		1000	mA
OUT	Maximum Output Current				150		mA
PSRR	Power Supply Rejection Ratio	$f = 1 \text{ kHz}, I_{OUT} = 1$	ImA to 150mA	55			
		$f = 10 \text{kHz}, I_{OUT} = 150 \text{mA}$		35			dB

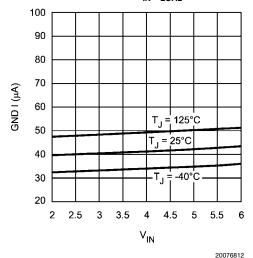
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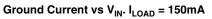
Symbol	Parameter		onditions	Тур	Limit		Units
Symbol	Falametei			тур	Min	Max	Units
		BW = 10Hz to	V <sub>OUT</sub> = 0.8	60			
'n	Output noise Voltage (Note 10)	100kHz,	V <sub>OUT</sub> = 1.5	125			μV <sub>RMS</sub>
			V <sub>OUT</sub> = 3.3	180			
SHUTDOWN	Thermal Shutdown	Temperature		155			
		Hysteresis		15			− °C
nable Cont	trol Characteristics	•				•	
EN	Maximum Input Current at	V <sub>EN</sub> = 0.0V		0.001		0.1	
Note 12)	V <sub>EN</sub> Input	V <sub>EN</sub> = 6V		6	2.5	10	μΑ
, IL	Low Input Threshold	$V_{IN} = 2V \text{ to } 6V$				0.4	V
/ /H	High Input Threshold	$V_{IN} = 2V \text{ to } 6V$			0.95		V
iming Char	ů i				0.00		
-	Turn On Time (Note 10)	To 95% Level	V -08	80		150	1
ON		$V_{IN(MIN)}$ to 6.0V	$V_{OUT} = 0.8$				-
				105		200	µs
			V <sub>OUT</sub> = 3.3	175		250	
ransient	001	T <sub>rise</sub> = T <sub>fall</sub> = 30µs (Note 10)		8		16	mV (pk - pk)
lesponse		$\delta V_{IN} = 600 mV$					
lesponse	Load Transient Response ΙδV <sub>OUT</sub> Ι		(Note 10)I <sub>OUT</sub> = 1mA to				
lesponse		T <sub>rise</sub> = T <sub>fall</sub> = 1µs 150mA	(Note 10)I <sub>OUT</sub> = 1mA to	55		100	mV
Note 1: Abso guaranteed. C Characteristic Note 2: All Vo Note 3: For fu Package,AN- Note 4: Interr Note 5: The f each pin.	Load Transient Response $ \delta V_{OUT} $ Jute Maximum Ratings are limits beyond whi Departing Ratings do not imply guaranteed points tables. Oltages are with respect to the potential at the urther information on these packages please 1187 Leadless Leadframe Package. Inal thermal shutdown circuitry protects the de human body model is 100pF discharged thro	$T_{rise} = T_{fall} = 1 \mu s$ 150mA $C_{OUT} = 1 \mu F$ ich damage can occu erformance limits. Fo e GND pin. refer to the following evice from permanen rugh a 1.5kΩ resistor	r. Operating Ratings are condi r guaranteed performance limit application notes;AN-1112 Mi t damage. into each pin. The machine mo	tions under v is and associ icro SMD Par odel is a 200	ated test cont ckage Wafer pF capacitor o	on of the devi ditions, see th Level Chip S discharged d	ice is ne Electrical cale irectly into
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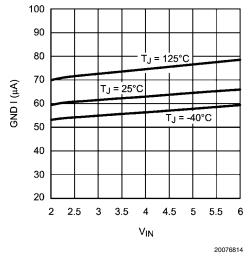
 $\label{eq:constraint} \begin{array}{l} \textbf{Typical Performance Characteristics.} \\ \mu\text{F Ceramic, } V_{\text{IN}} = V_{\text{OUT}(\text{NOM})} + 1.0\text{V}, \ T_{\text{A}} = 25^{\circ}\text{C}, \ V_{\text{OUT}(\text{NOM})} = 1.5\text{V} \ , \ \text{Shutdown pin is tied to } V_{\text{IN}}. \end{array}$ 

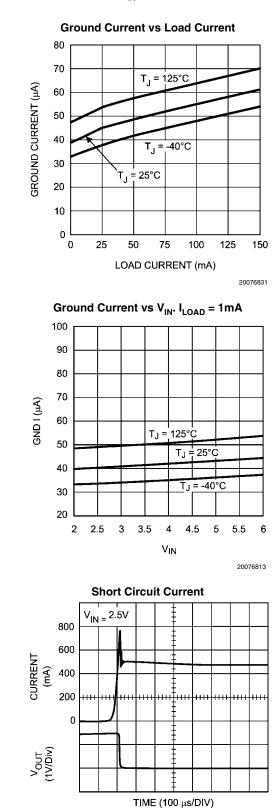


Ground Current vs  $V_{IN}$ .  $I_{LOAD} = 0mA$ 

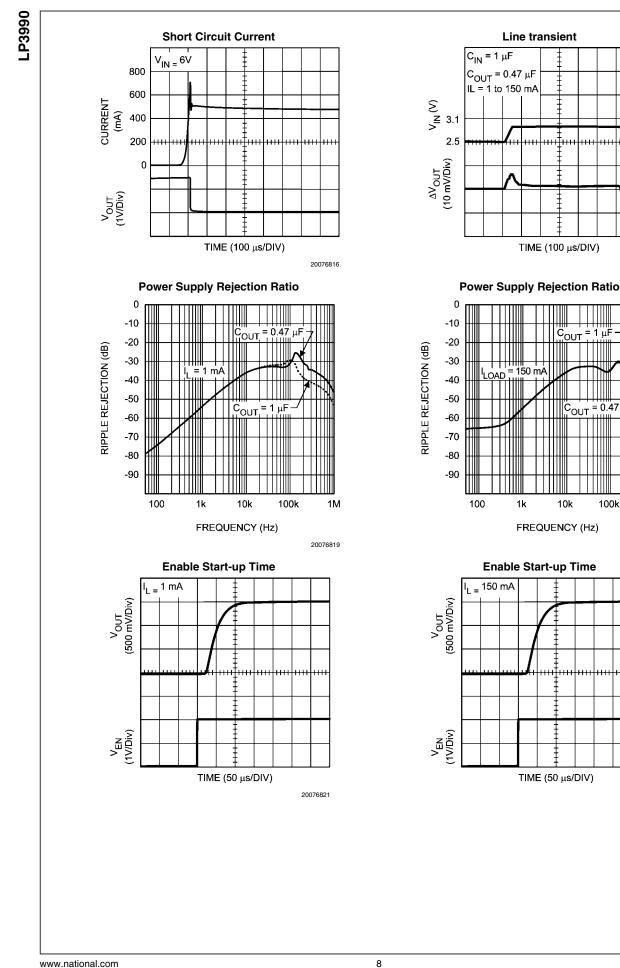








LP3990



20076817

C<sub>OUT</sub> = 1 μF

C<sub>OUT</sub> = 0.47 μF

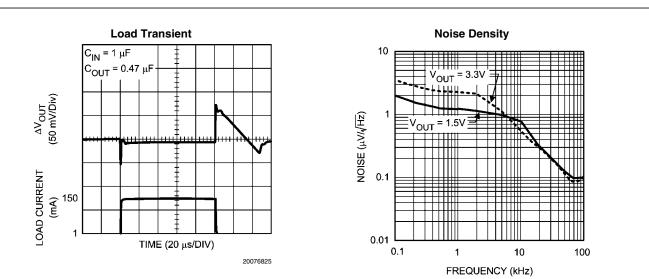
100k

1M

20076820

20076822

10k



### **Application Hints**

#### **EXTERNAL CAPACITORS**

In common with most regulators, the LP3990 requires external capacitors for regulator stability. The LP3990 is specifically designed for portable applications requiring minimum board space and smallest components. These capacitors must be correctly selected for good performance.

#### **INPUT CAPACITOR**

An input capacitor is required for stability. It is recommended that a  $1.0\mu$ F capacitor be connected between the LP3990 input pin and ground (this capacitance value may be increased without limit).

This capacitor must be located a distance of not more than 1cm from the input pin and returned to a clean analogue ground. Any good quality ceramic, tantalum, or film capacitor may be used at the input.

**Important:** To ensure stable operation it is essential that good PCB design practices are employed to minimize ground impedance and keep input inductance low. If these conditions cannot be met, or if long leads are used to connect the battery or other power sorce to the LP3990, then it is recommended that the input capacitor is increased. Also, tantalum capacitors can suffer catastrophic failures due to surge current when connected to a low-impedance source of power (like a battery or a very large capacitor). If a tantalum capacitor is used at the input, it must be guaranteed by the manufacturer to have a surge current rating sufficient for the application.

There are no requirements for the ESR (Equivalent Series Resistance) on the input capacitor, but tolerance and temperature coefficient must be considered when selecting the capacitor to ensure the capacitance will remain approximately  $1.0\mu$ F over the entire operating temperature range.

#### **OUTPUT CAPACITOR**

The LP3990 is designed specifically to work with very small ceramic output capacitors. A  $1.0\mu$ F ceramic capacitor (temperature types Z5U, Y5V or X7R) with ESR between  $5m\Omega$  to  $500m\Omega$ , is suitable in the LP3990 application circuit.

For this device the output capacitor should be connected between the  $\rm V_{OUT}$  pin and ground.

It is also possible to use tantalum or film capacitors at the device output,  $C_{OUT}$  (or  $V_{OUT}$ ), but these are not as attractive for reasons of size and cost (see the section Capacitor Characteristics).

The output capacitor must meet the requirement for the minimum value of capacitance and also have an ESR value that is within the range  $5m\Omega$  to  $500m\Omega$  for stability.

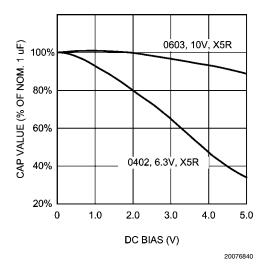
#### **NO-LOAD STABILITY**

The LP3990 will remain stable and in regulation with no external load. This is an important consideration in some circuits, for example CMOS RAM keep-alive applications.

#### **CAPACITOR CHARACTERISTICS**

The LP3990 is designed to work with ceramic capacitors on the output to take advantage of the benefits they offer. For capacitance values in the range of  $0.47\mu$ F to  $4.7\mu$ F, ceramic capacitors are the smallest, least expensive and have the lowest ESR values, thus making them best for eliminating high frequency noise. The ESR of a typical  $1.0\mu$ F ceramic capacitor is in the range of  $20m\Omega$  to  $40m\Omega$ , which easily meets the ESR requirement for stability for the LP3990. For both input and output capacitors, careful interpretation of the capacitor specification is required to ensure correct device operation. The capacitor value can change greatly, depending on the operating conditions and capacitor type.

In particular, the output capacitor selection should take account of all the capacitor parameters, to ensure that the specification is met within the application. The capacitance can vary with DC bias conditions as well as temperature and frequency of operation. Capacitor values will also show some decrease over time due to aging. The capacitor parameters are also dependant on the particular case size, with smaller sizes giving poorer performance figures in general. As an example, Figure 1 shows a typical graph comparing different capacitor case sizes in a Capacitance vs. DC Bias plot. As shown in the graph, increasing the DC Bias condition can result in the capacitance value falling below the minimum value given in the recommended capacitor specifications table (0.7µF in this case). Note that the graph shows the capacitance out of spec for the 0402 case size capacitor at higher bias voltages. It is therefore recommended that the capacitor manufacturers' specifications for the nominal value capacitor are consulted for all conditions, as some capacitor sizes (e.g. 0402) may not be suitable in the actual application.



#### FIGURE 1. Graph Showing a Typical Variation in Capacitance vs DC Bias

The ceramic capacitor's capacitance can vary with temperature. The capacitor type X7R, which operates over a temperature range of -55°C to +125°C, will only vary the capacitance to within  $\pm 15\%$ . The capacitor type X5R has a similar tolerance over a reduced temperature range of -55°C to +85°C. Many large value ceramic capacitors, larger than 1µF are manufactured with Z5U or Y5V temperature characteristics. Their capacitance can drop by more than 50% as the temperature varies from 25°C to 85°C. Therefore X7R is recommended over Z5U and Y5V in applications where the ambient temperature will change significantly above or below 25°C.

Tantalum capacitors are less desirable than ceramic for use as output capacitors because they are more expensive when comparing equivalent capacitance and voltage ratings in the  $0.47\mu$ F to  $4.7\mu$ F range.

Another important consideration is that tantalum capacitors have higher ESR values than equivalent size ceramics. This means that while it may be possible to find a tantalum capacitor with an ESR value within the stable range, it would have to be larger in capacitance (which means bigger and more

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costly) than a ceramic capacitor with the same ESR value. It should also be noted that the ESR of a typical tantalum will increase about 2:1 as the temperature goes from 25°C down to -40°C, so some guard band must be allowed.

### ENABLE CONTROL

The LP3990 features an active high Enable pin, V<sub>EN</sub>, which turns the device on when pulled high. When not enabled the regulator output is off and the device typically consumes 2nA. If the application does not require the Enable switching feature, the V<sub>EN</sub> pin should be tied to V<sub>IN</sub> to keep the regulator output permanently on.

To ensure proper operation, the signal source used to drive the V<sub>EN</sub> input must be able to swing above and below the specified turn-on/off voltage thresholds listed in the Electrical Characteristics section under V<sub>IL</sub> and V<sub>IH</sub>.

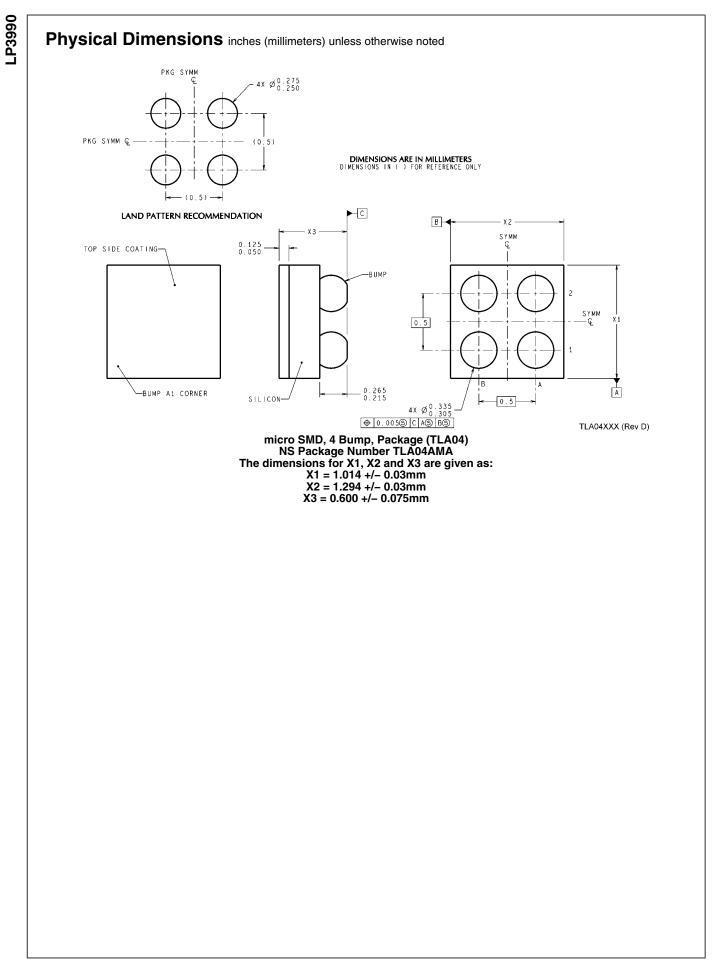
#### Micro SMD MOUNTING

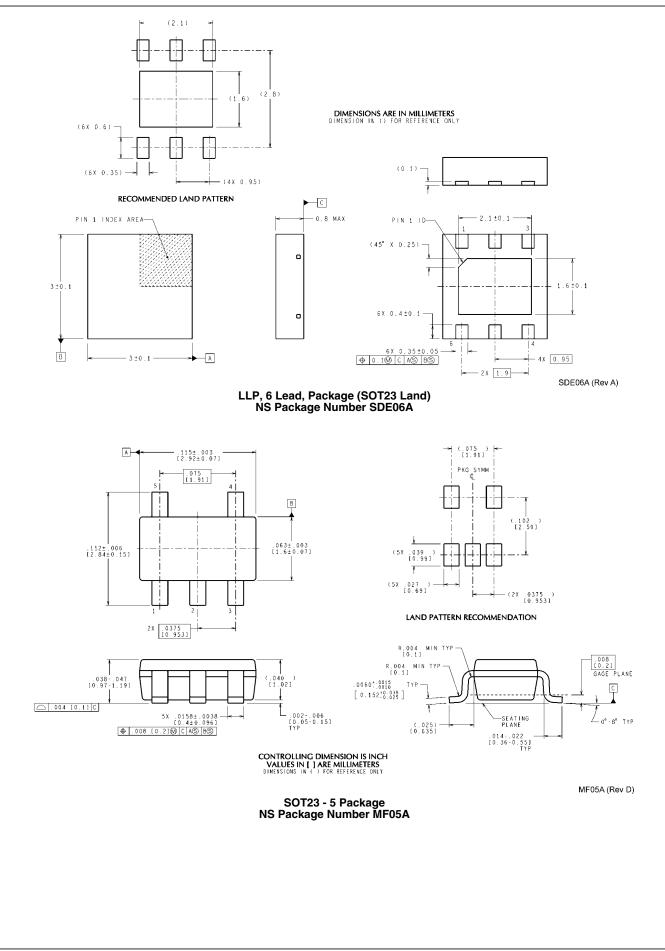
The micro SMD package requires specific mounting techniques, which are detailed in National Semiconductor Application Note AN-1112. For best results during assembly, alignment ordinals on the PC board may be used to facilitate placement of the micro SMD device.

### Micro SMD LIGHT SENSITIVITY

Exposing the micro SMD device to direct light may affect the operation of the device. Light sources, such as halogen lamps, can affect electrical performance, if placed in close proximity to the device.

Light with wavelengths in the infra-red portion of the spectrum is the most detrimental, and so, fluorescent lighting used inside most buildings, has little or no effect on performance.





LP3990

# Notes

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